

## 1. General description

Standard reverse recovery power diode in a TO263 package.



## 2. Features and benefits

- Low forward voltage drop
- Low leakage current
- High voltage capability
- High inrush current capability

## 3. Applications

- Oring diode
- Bypass diode
- Input rectifier for bridge configurations

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
<b>Absolute maximum rating</b>							
$V_{RRM}$	repetitive peak reverse voltage			1600			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 97$ °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		35			A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; <a href="#">Fig. 4</a>		400			A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse		435			A
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward voltage	$I_F = 35$ A; $T_j = 25$ °C; <a href="#">Fig. 6</a>		-	1.18	1.40	V
$I_R$	reverse current	$V_R = 1600$ V; $T_j = 25$ °C		-	-	50	$\mu$ A

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode		
2	K	cathode [1]		
3	A	anode		
mb	K	mounting base; connected to cathod		

[1] It is not possible to connect to pin 2 of the TO263 package.

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WND35P16B	TO263	WND35P16BJ	Reel	800	TO263N (N)	28-Sep-2016
					TO263P (P)	12-Jun-2023

## 7. Marking

Table 4. Marking codes

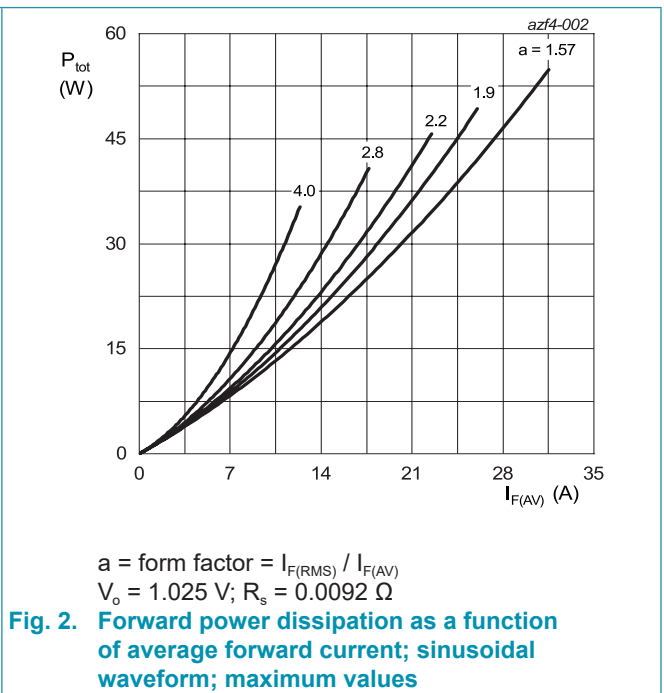
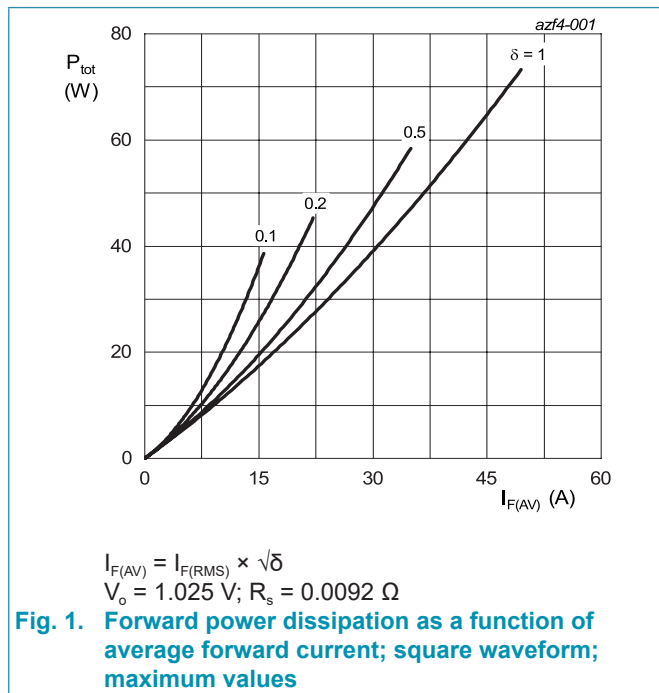
Type number	Marking codes	
	Assembly factory: N	Assembly factory: P
WND35P16B	WND35P16B PJNxxxx xx	WND35P16B PJPxxxx xx

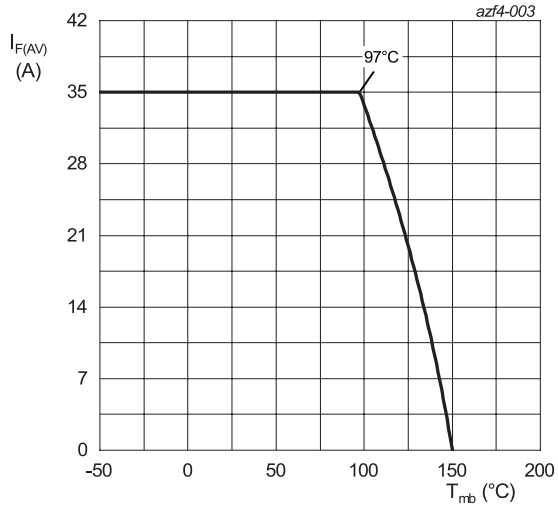
## 8. Limiting values

**Table 5. Limiting values**

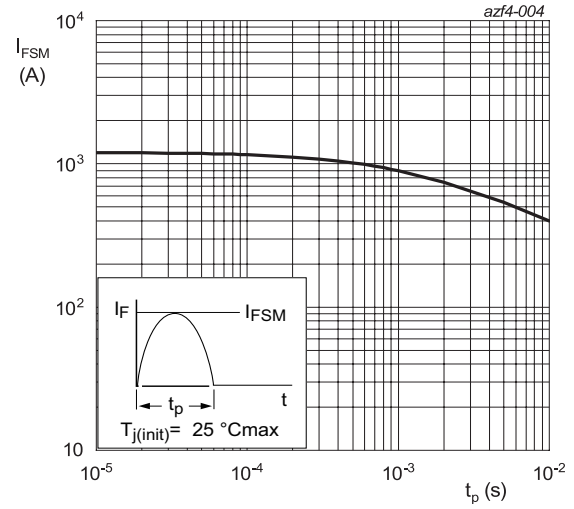
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			1600	V
$V_{RWM}$	crest working reverse voltage			1600	V
$V_R$	reverse voltage	DC		1600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 97\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		35	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>		400	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; sine-wave pulse		435	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; sine-wave pulse		800	A <sup>2</sup> s
$T_{stg}$	storage temperature			-40 to 150	°C
$T_j$	junction temperature			-40 to 150	°C





**Fig. 3. Forward current as a function of mounting base temperature; maximum values**



**Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values**

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Values	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>		-	-	0.9	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	50	-	K/W

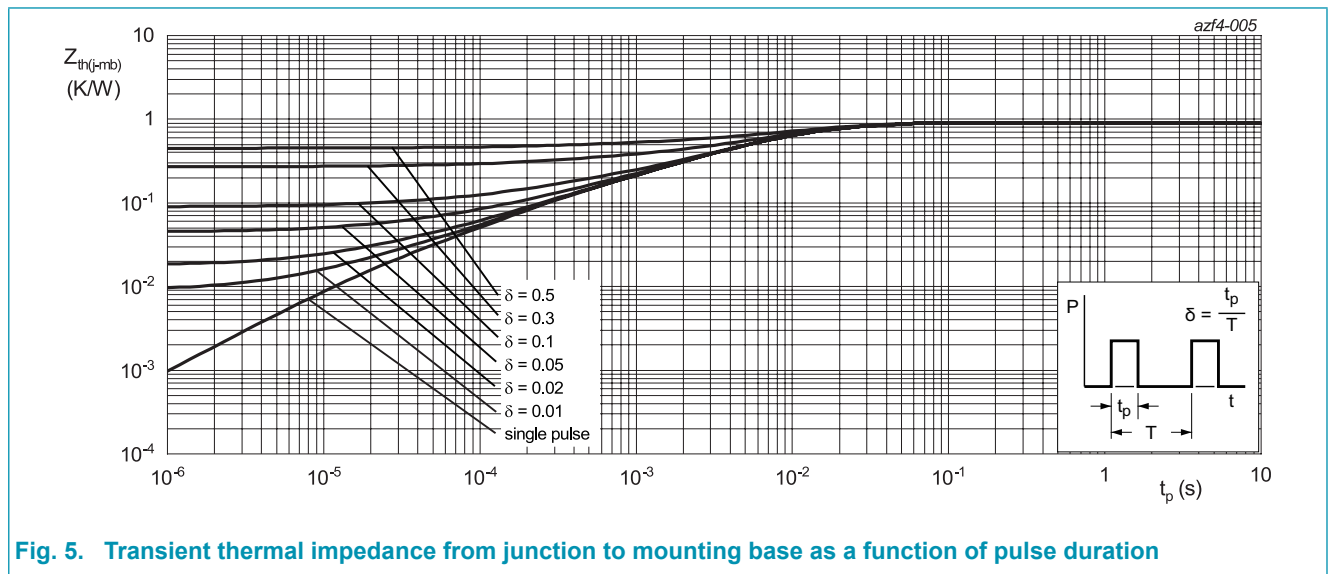
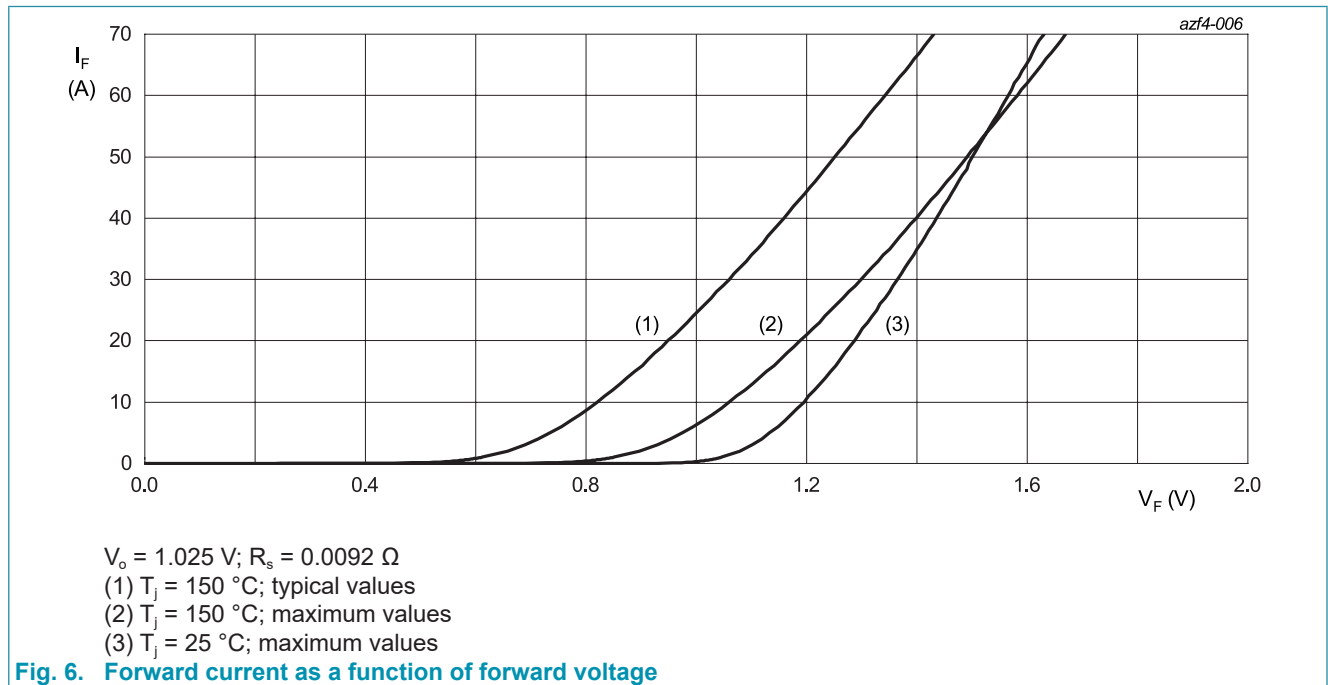


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

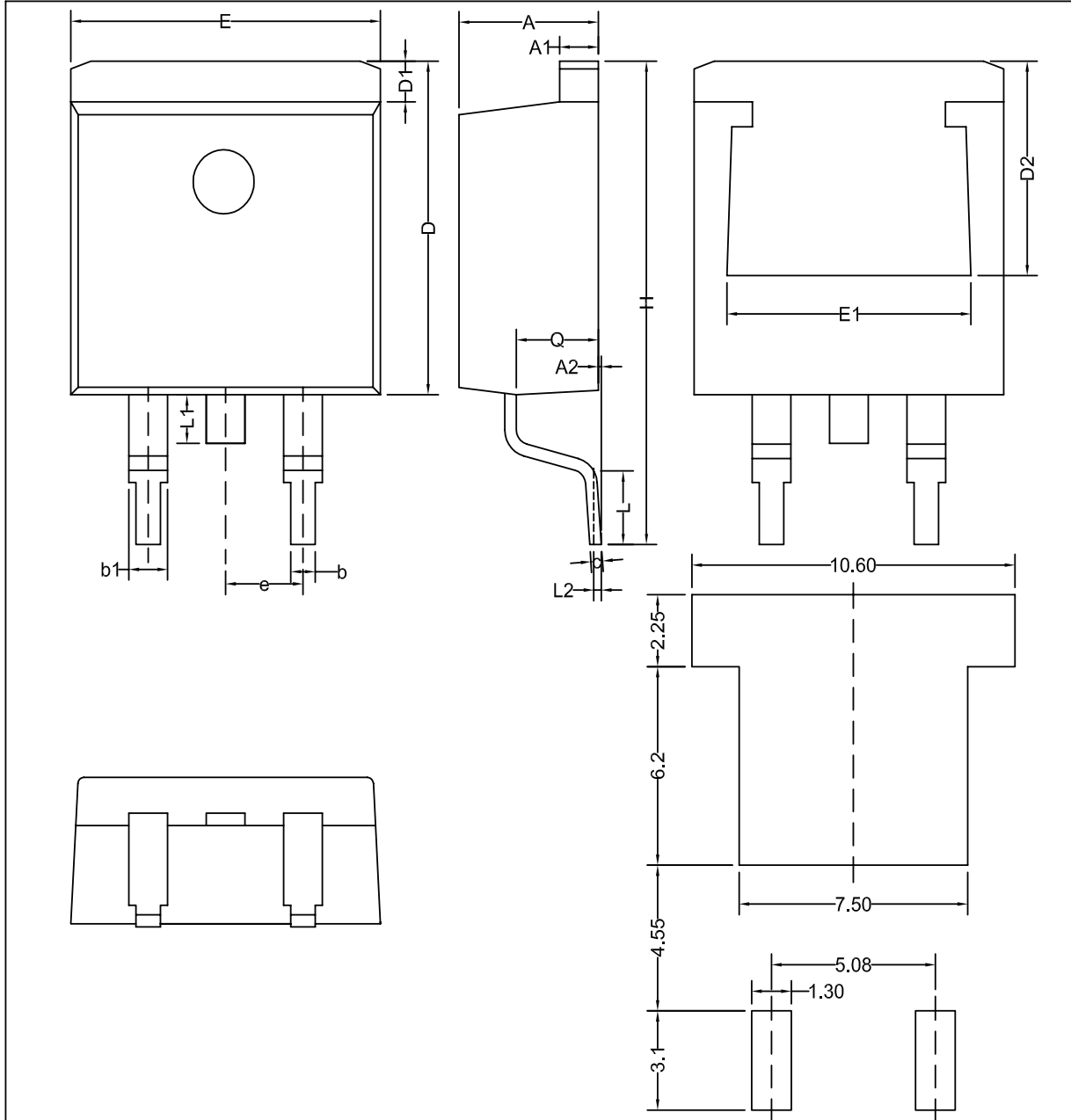
Symbol	Parameter	Conditions	Notes	Values	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward current	$I_F = 35\text{ A}; T_j = 25\text{ °C}; \text{Fig. 6}$		-	1.18	1.40	V
		$I_F = 35\text{ A}; T_j = 150\text{ °C}; \text{Fig. 6}$		-	1.15	1.35	V
		$I_F = 25\text{ A}; T_j = 25\text{ °C}; \text{Fig. 6}$		-	1.10	1.30	V
		$I_F = 25\text{ A}; T_j = 150\text{ °C}; \text{Fig. 6}$		-	1.05	1.25	V
$I_R$	reverse current	$V_R = 1600\text{ V}; T_j = 25\text{ °C}$		-	-	50	$\mu\text{A}$
		$V_R = 1600\text{ V}; T_j = 150\text{ °C}$		-	-	1	mA



### 11. Package outline

Assembly factory: N

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) TO263



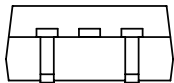
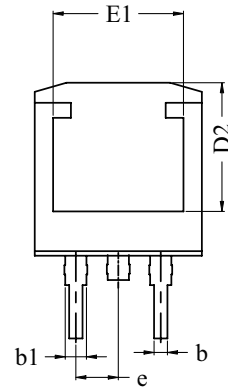
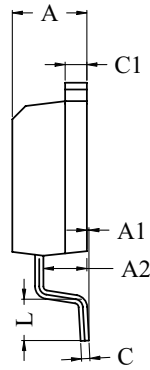
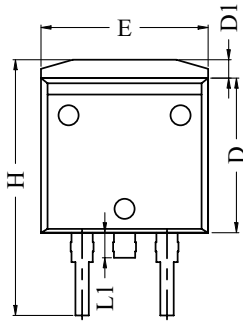
Recommended Footprint

Unit	A	A1	A2	b	b1	c	D	D1	D2	e	E	E1	H	L	L1	L2	Q
min	4.10	1.22	0.00	0.60	1.05	0.34	---	1.20	6.60	2.54 (BSC)	9.70	7.80	14.80	2.10	---	0.25 (BSC)	2.20
max	4.70	1.40	0.25	0.90	1.45	0.64	11.00	1.60	---	---	10.30	---	15.80	2.90	1.75	---	2.79

Assembly factory: P

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

TO263



Dim	All Dimensions in Millimeters		
	Min	Typ	Max
A	4.30	4.46	4.60
A1	0	0.13	0.25
A2	2.50	2.60	2.70
b	0.70	0.80	0.90
b1	1.10	1.27	1.45
C	0.40	0.52	0.60
C1	1.17	1.30	1.40
D	9.10	9.25	9.40
D1	1.00	1.10	1.30
D2	7.40	7.70	8.00
E	9.80	10.00	10.20
E1	7.60	7.80	8.00
e	2.54 BSC		
H	14.80	15.30	15.80
L	2.10	2.47	2.80
L1	1.30	1.50	1.70



## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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